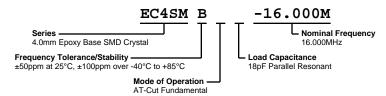
# EC4SMB-16.000M

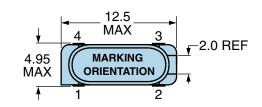


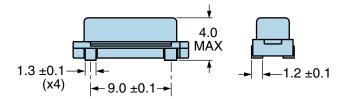


ELECTRICAL SPECIFICATIONS		
Nominal Frequency	16.000MHz	
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over -40°C to +85°C	
Aging at 25°C	±5ppm/year Maximum	
Load Capacitance	18pF Parallel Resonant	
Shunt Capacitance (C0)	7pF Maximum	
Equivalent Series Resistance	50 Ohms Maximum	
Mode of Operation	AT-Cut Fundamental	
Drive Level	1mWatts Maximum	
Storage Temperature Range	-40°C to +85°C	
Insulation Resistance	500 Megaohms Minimum at 100Vdc	

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS		
Fine Leak Test	MIL-STD-883, Method 1014 Condition A	
Gross Leak Test	MIL-STD-883, Method 1014 Condition C	
Mechanical Shock	MIL-STD-202, Method 213 Condition C	
Resistance to Soldering Heat	MIL-STD-202, Method 210	
Resistance to Solvents	MIL-STD-202, Method 215	
Solderability	MIL-STD-883, Method 2003	
Temperature Cycling	MIL-STD-883, Method 1010	
Vibration	MIL-STD-883, Method 2007 Condition A	

### **MECHANICAL DIMENSIONS (all dimensions in millimeters)**





PIN	CONNECTION
1	Connected to Pin 4 and to Crystal
2	Connected to Pin 3 and to Crystal
3	Connected to Pin 2 and to Crystal
4	Connected to Pin 1 and to Crystal

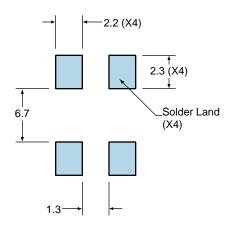
LINE	MARKING
1	E16.000 E=Ecliptek Designator

# EC4SMB-16.000M



### **Suggested Solder Pad Layout**

All Dimensions in Millimeters



All Tolerances are ±0.1

## EC4SMB-16.000M



## **Recommended Solder Reflow Methods**



### Low Temperature Infrared/Convection 225°C

T <sub>s</sub> MAX to T <sub>L</sub> (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T <sub>s</sub> MIN)	N/A
- Temperature Typical (T <sub>s</sub> TYP)	150°C
- Temperature Maximum (T <sub>s</sub> MAX)	N/A
- Time (t <sub>s</sub> MIN)	30 - 60 Seconds
Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )	5°C/second Maximum
Time Maintained Above:	
- Temperature (T∟)	150°C
- Time (t∟)	200 Seconds Maximum
Peak Temperature (T <sub>P</sub> )	225°C Maximum
Target Peak Temperature (T <sub>P</sub> Target)	225°C Maximum 2 Times
Time within 5°C of actual peak (tp)	80 seconds Maximum 2 Times
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

### **Low Temperature Manual Soldering**

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

#### **High Temperature Manual Soldering**

260°C Maximum for 5 seconds Maximum, 2 times Maximum.